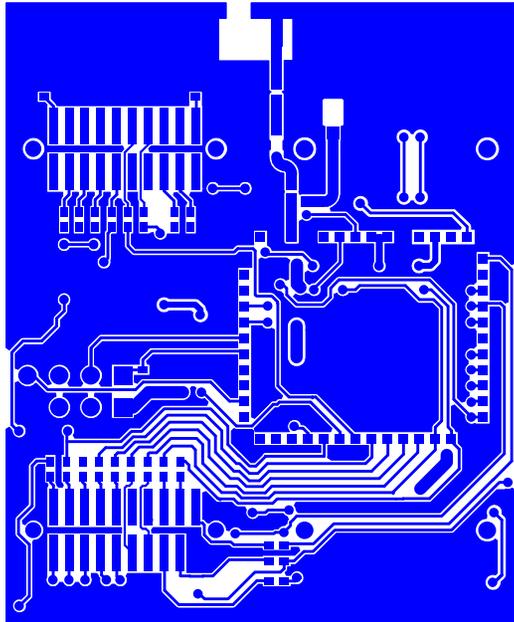


TIDC-WIFI-METER-READING

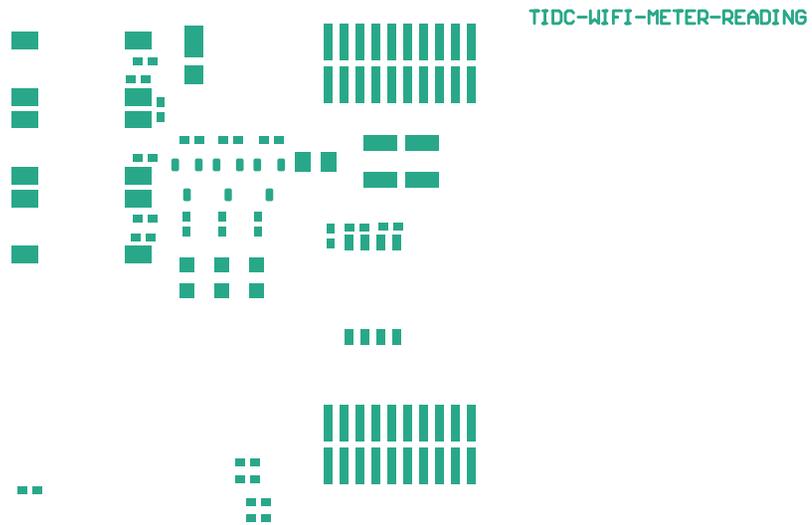
Top Layer



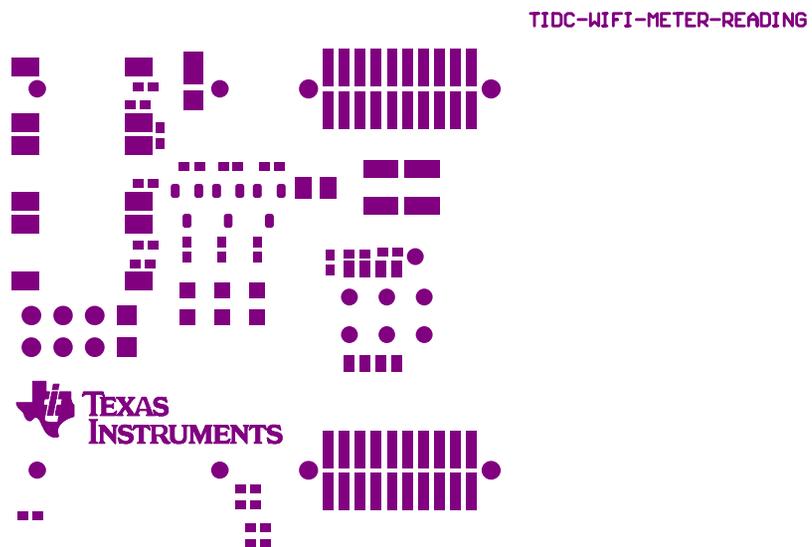
TIDC-WIFI-METER-READING

SVN: Not In VersionControl

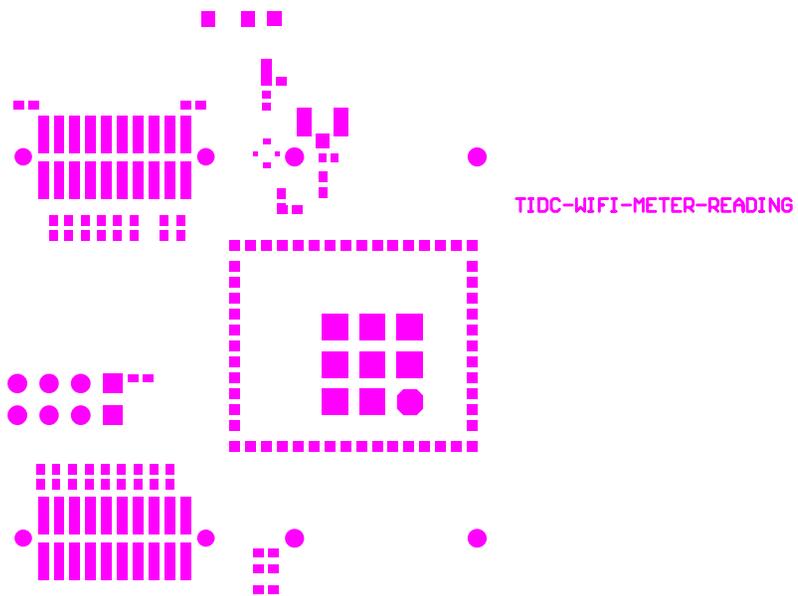
Bottom Layer



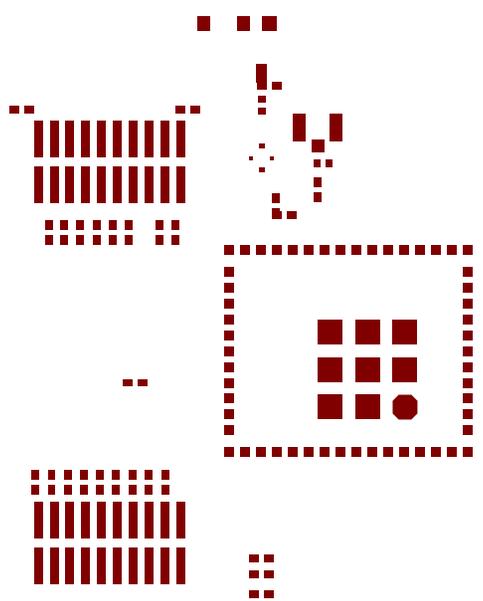
Top Paste



Top Solder

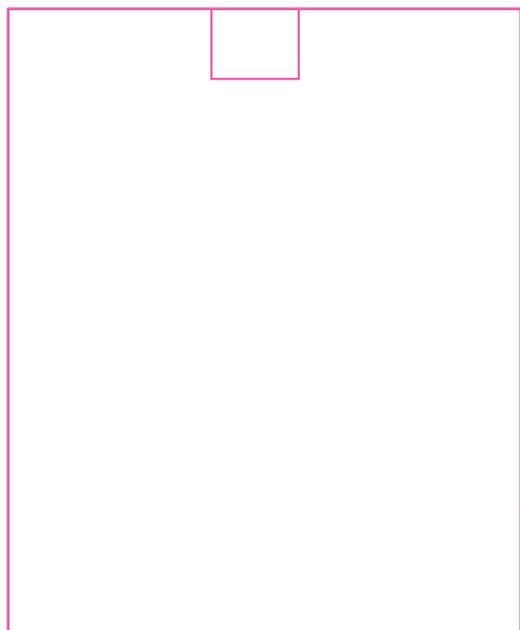


Bottom Solder



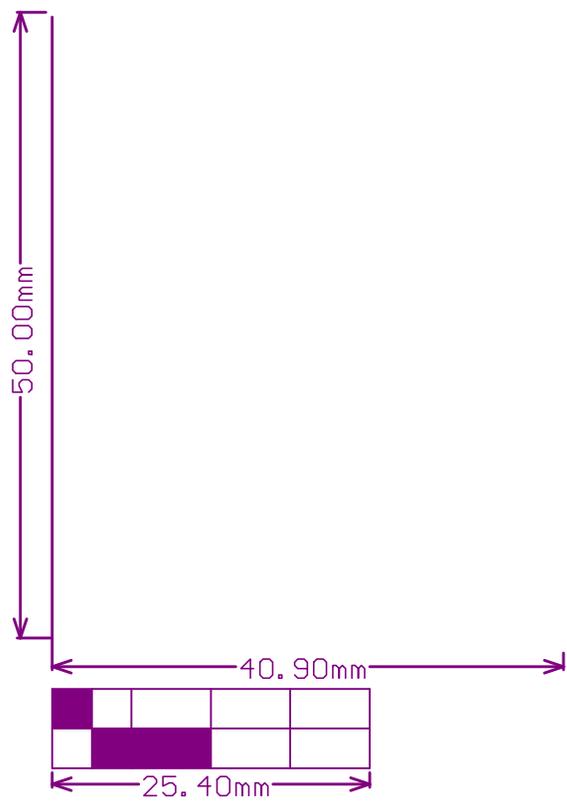
TIDC-WIFI-METER-READING

Bottom Paste



TIDC-WIFI-METER-READING

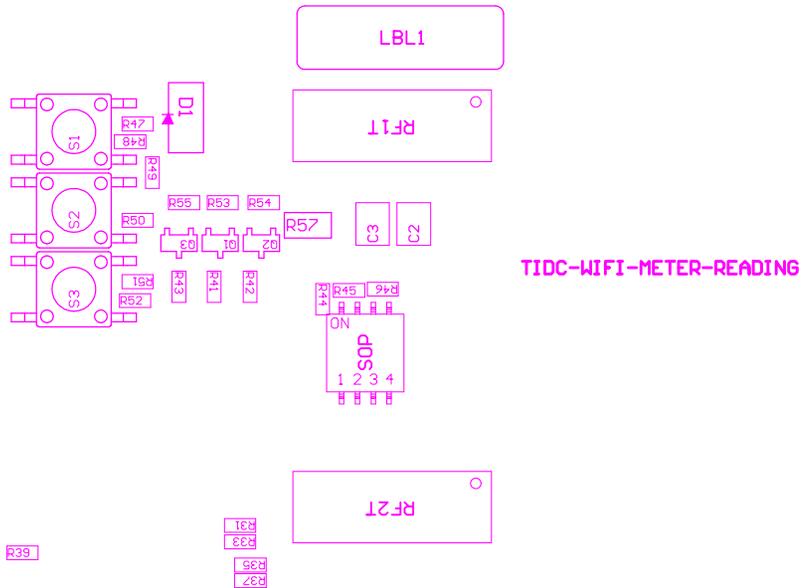
M1 Board Outline



TIDC-WIFI-METER-READING

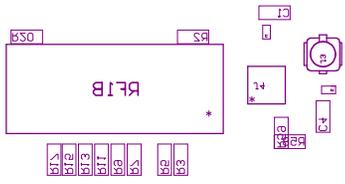
M2 Board Dimensions

- ZZ4 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.
- ZZ1 ■ Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.
- ZZ2 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.
- ZZ3 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.



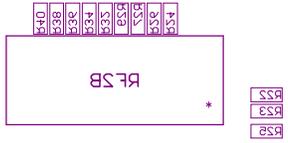
COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM TOP SIDE	BOARD #: TIDC-WIFI-METER-READING	SUN REV: Not In VersionControl
IGNORE ->		
PLOT NAME = CC3200MOD_CONV.GM5	GENERATED : 9/9/2015 17:01:14	TEXAS INSTRUMENTS



TIDC-WIFI-METER-READING

R52



ASSEMBLY VARIANT: [No Variations]
 COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.

PCB VIEWED FROM BOTTOM SIDE	BOARD # : TIDC-WIFI-METER-READING	SUN REV: Not In VersionControl
IGNORE ->		
PLOT NAME = CC3200MOD_CONV.GM6	GENERATED : 2/2/2015 17:01:14	TEXAS INSTRUMENTS

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